



TE Internal #: 2-2388957-3
Board-to-Board, 98 Position, 1 mm [.04 in] Centerline, Vertical,
Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in], PCI & PCI
Express Connectors
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Connector System: **Board-to-Board**
Number of Positions: **98**
PCI Generation: **5**
Centerline (Pitch): **1 mm [.04 in]**
Termination Post & Tail Length: **1.1 mm [.043 in]**

Features

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Tab

Contact Features

Contact Current Rating (Max)	1.1 A
	30 µin

Termination Features

Termination Method to PCB	Surface Mount
Termination Post & Tail Length	1.1 mm[.043 in]

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Sealable	No

Configuration Features

Number of Positions	98
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PCB Mount Orientation	Vertical
Ejector	Without

Body Features

Primary Product Color	Black
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Housing Features

Centerline (Pitch)	1 mm[.04 in]
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Dimensions

Connector Height	11.25 mm[.44 in]
Connector Width	8.2 mm[.32 in]

Usage Conditions

Operating Temperature Range	-40 – 85 °C[-40 – 185 °F]
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Operation/Application

Circuit Application	High Speed Data
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Industry Standards

PCI Generation	5
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Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability



Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

PCIE5,SMT,2X2.76TAB,98P,30",WO ML,HT

English

CAD Files

Customer View Model

ENG_CVM_CVM_2-2388957-3_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-2388957-3_A.3d_stp.zip

English

Customer View Model

ENG_CVM_CVM_2-2388957-3_A.2d_dxf.zip

English

3D PDF

3D

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Product Specifications

Application Specification

English